(Name of the document) Drawing

Fig. 1



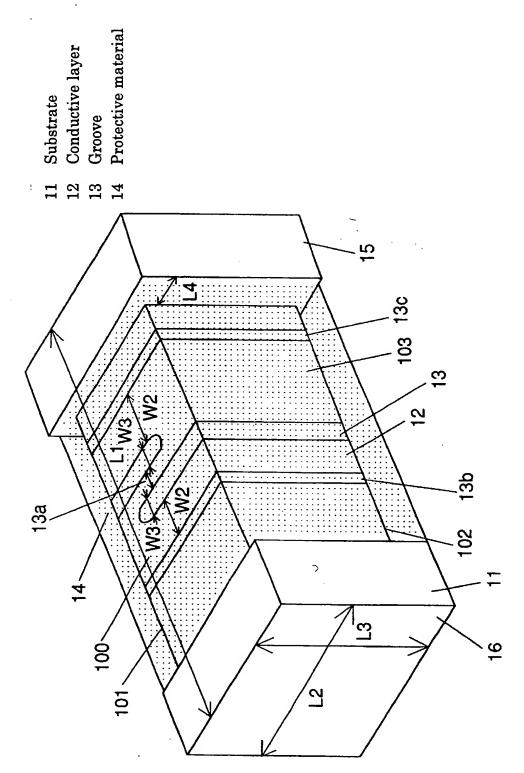




Fig. 2

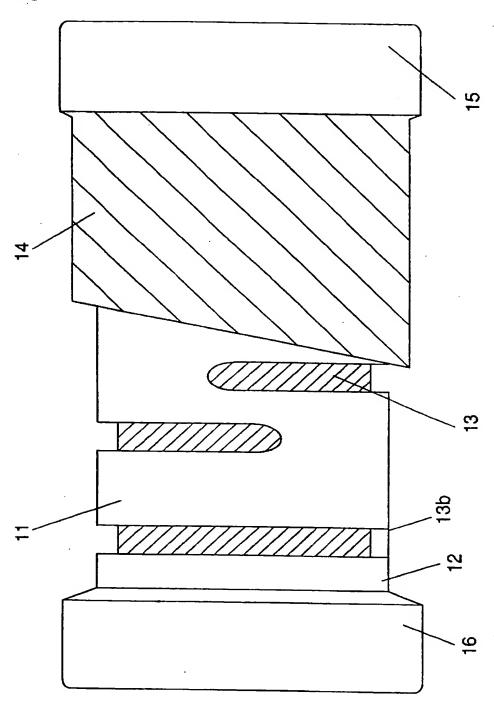
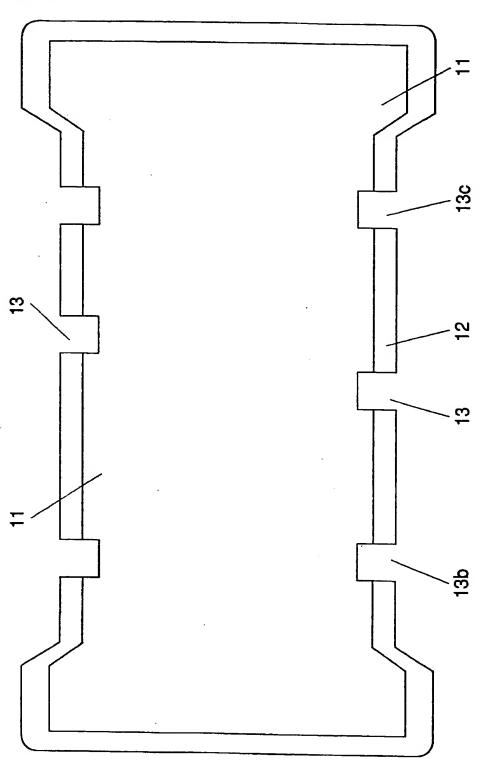




Fig. 3



MAR 1 5 2004 05

Fig. 4

@

(a)

11a Central portion 11b, 11c End portion

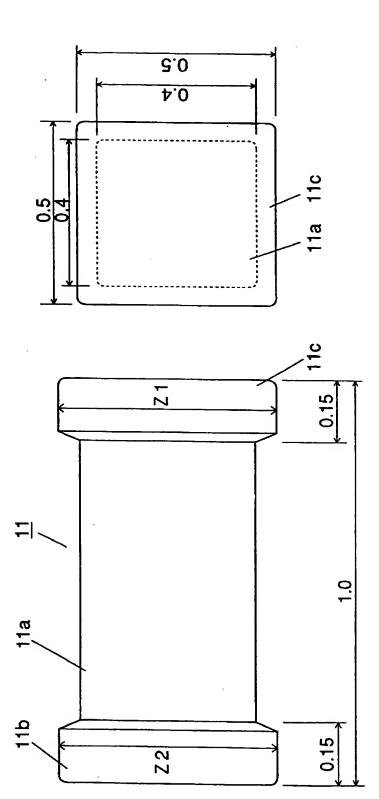
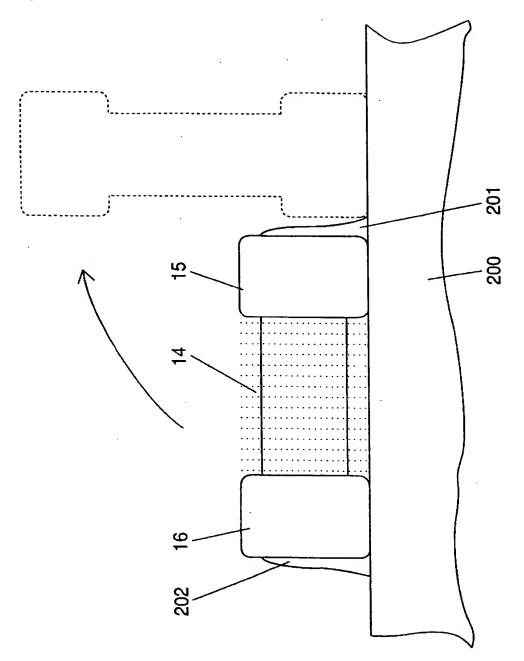


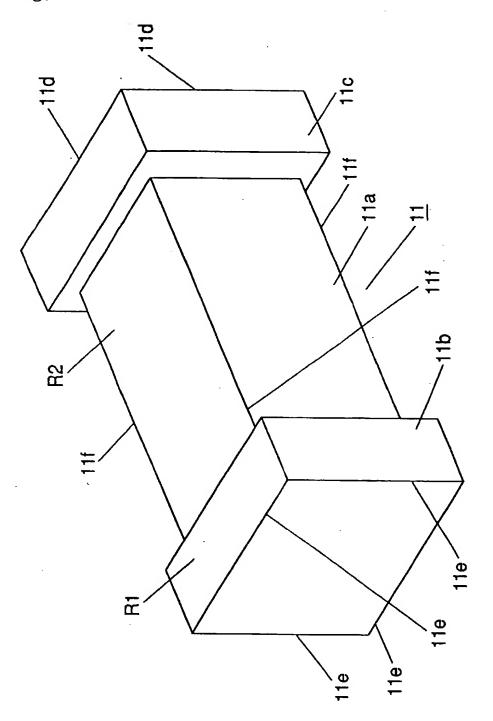


Fig. 5



MAR 1 5 2004 SE

Fig. 6







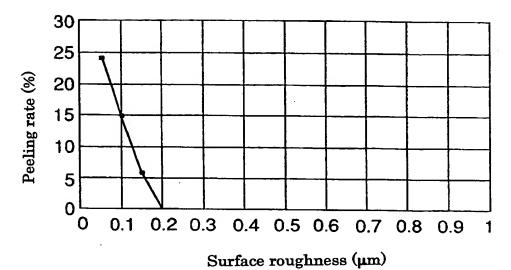


Fig. 8

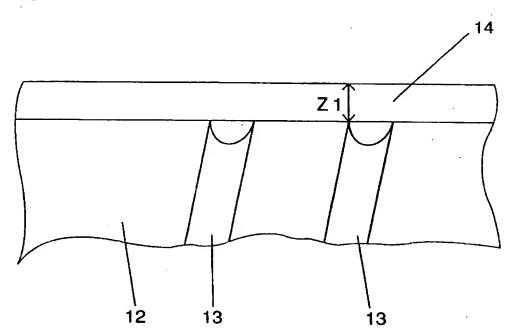
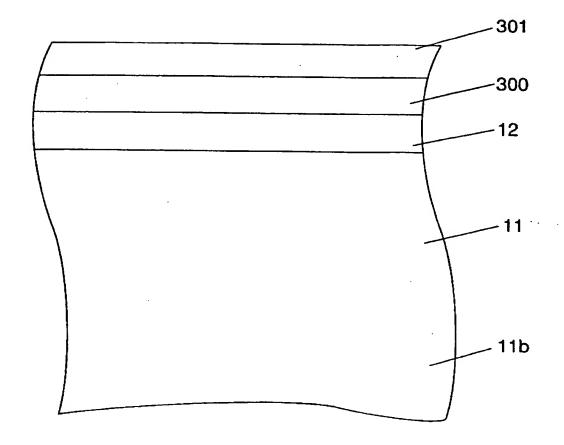




Fig. 9





:Fig. 10

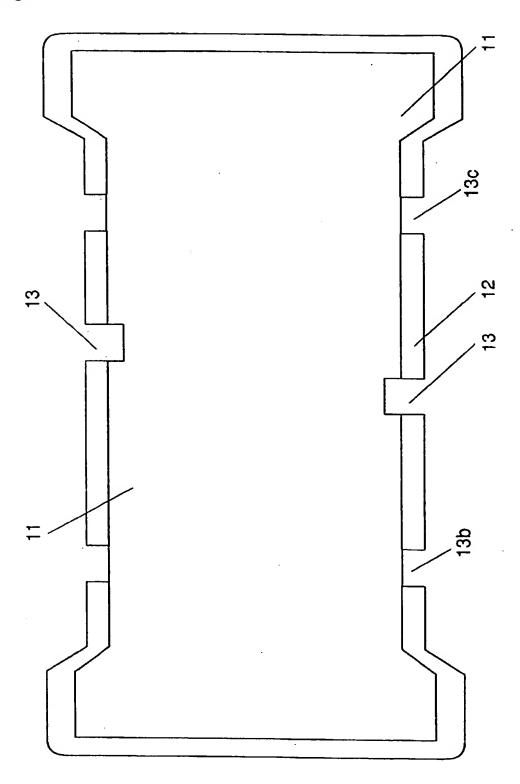
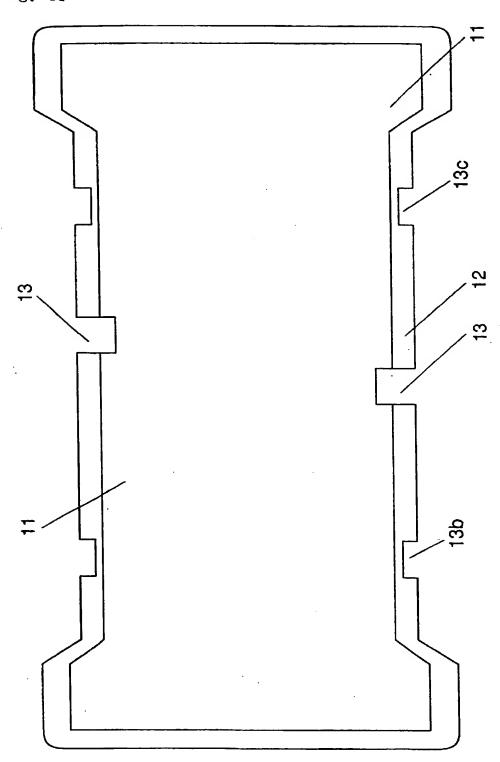




Fig. 11



MAR 1 5 2004 5 30 HE

Substrate 5 Conductive layer Groove Protective material

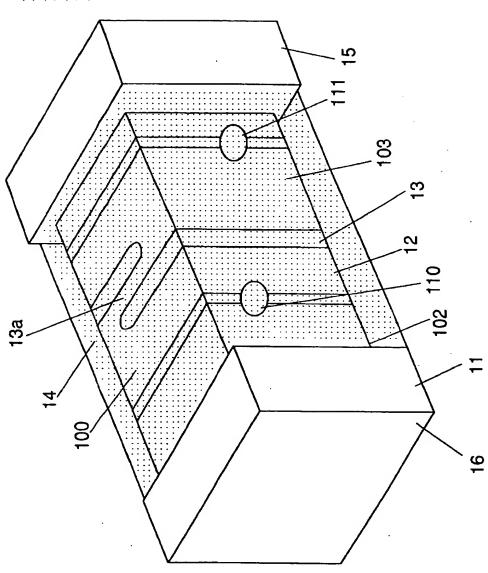


Fig. 13



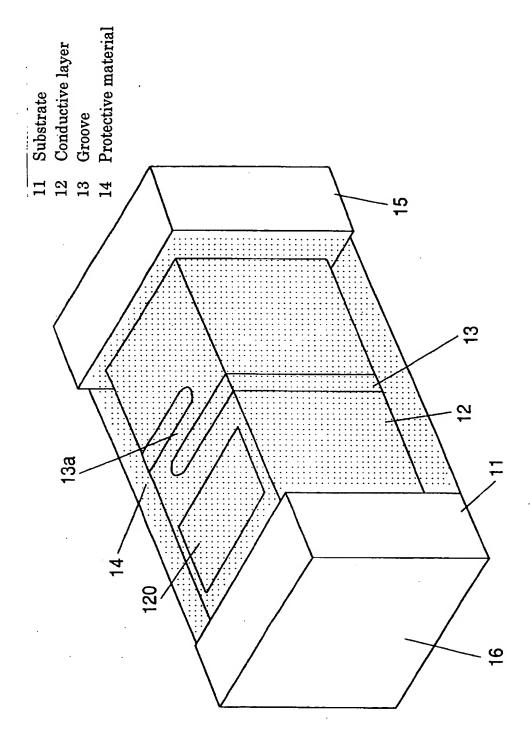




Fig. 14

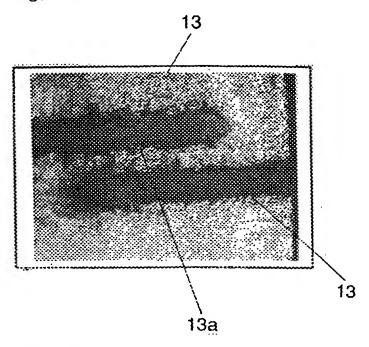


Fig. 15

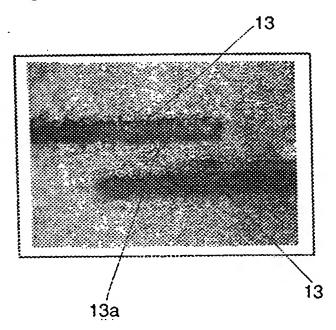
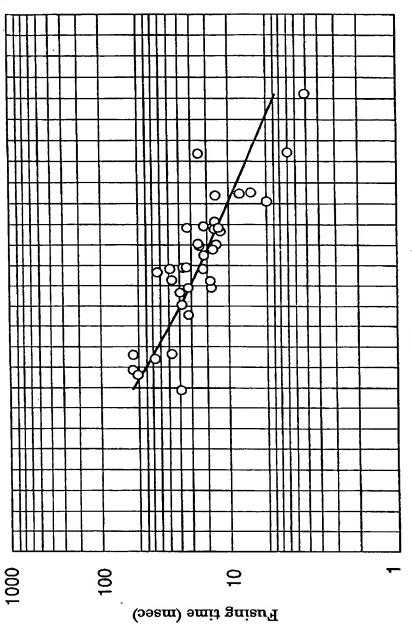




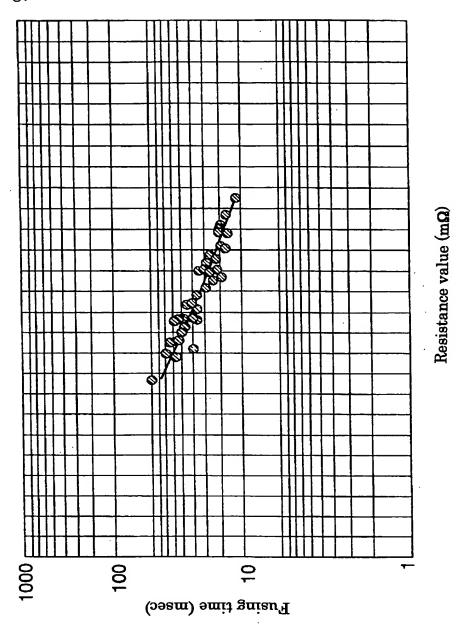
Fig. 16



Resistance value (mQ)



Fig. 17



51



Fig. 18

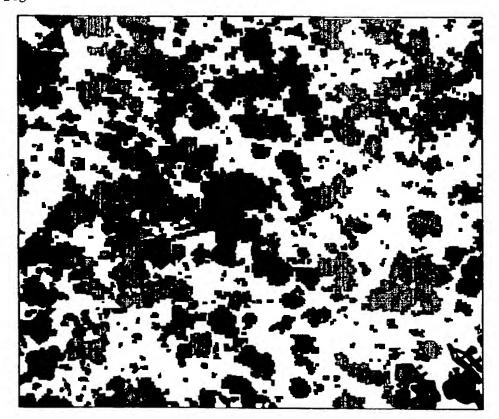




Fig. 19

